

OSG60R108xZF_Datasheet



Enhancement Mode N-Channel Power MOSFET

Features

- ◆ Ultra-fast and robust body diode
- ◆ Low $R_{DS(on)}$ & FOM
- ◆ Excellent low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

Applications

- ◆ Lighting
- ◆ Server power supply
- ◆ Telecom
- ◆ Solar invertor



■ General Description

OSG60R108xZF use advanced GreenMOS™ technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device offers extremely fast and robust body diode, and is suitable for telecom and power supplies.

◆ $V_{DS, min@Tjmax}$	650 V
◆ $I_D, pulse$	90 A
◆ $R_{DS(ON)}, \text{max @ } VGS=10 \text{ V}$	108 mΩ
◆ Q_g	37.1 nC

■ Schematic and Package Information

Schematic Diagram	Pin Assignment-Top View			
		TO263		TO247
		TO220		TO220F

■ Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	600	V
Gate source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾	I_D	30	A
Continuous drain current ¹⁾ $T_j=100^\circ\text{C}$		19	
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D, \text{pulse}}$	90	A
Power dissipation ³⁾ for TO263, TO247, TO220, $T_C=25^\circ\text{C}$	P_D	219	W
Power dissipation ³⁾ for TO220F, $T_C=25^\circ\text{C}$		34	
Single pulsed avalanche energy ⁵⁾	E_{AS}	1000	mJ
MOSFET dV/dt ruggedness, $V_{DS}=0...480 \text{ V}$	dV/dt	50	V/ns
Reverse diode dV/dt, $V_{DS}=0...480 \text{ V}, I_{SD} \leq I_D$	dV/dt	50	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C



■ Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO247/TO263/TO220	TO220F	
Thermal resistance, junction-case	R_{\thetaJC}	0.57	3.7	°C/W
Thermal resistance, junction-ambient ⁴⁾	R_{\thetaJA}	62	62.5	°C/W

■ Electrical Characteristics at $T_j=25$ °C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	600			V	$V_{GS}=0$ V, $I_D=1$ mA
		650	735			$V_{GS}=0$ V, $I_D=1$ mA, $T_j=150$ °C
Gate threshold voltage	$V_{GS(th)}$	3.0		4.5	V	$V_{DS}=V_{GS}$, $I_D=1$ mA
Drain-source on-state resistance	$R_{DS(ON)}$		0.085	0.108	Ω	$V_{GS}=10$ V, $I_D=15$ A
			0.2			$V_{GS}=10$ V, $I_D=15$ A, $T_j=150$ °C
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=30$ V
				-100		$V_{GS}=-30$ V
Drain-source leakage current	I_{DSS}			10	μ A	$V_{DS}=600$ V, $V_{GS}=0$ V

■ Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}		2674.5		pF	$V_{GS}=0$ V, $V_{DS}=50$ V, $f=100$ kHz
Output capacitance	C_{oss}		246.0		pF	
Reverse transfer capacitance	C_{rss}		9.6		pF	
Turn-on delay time	$t_{d(on)}$		67.4		ns	$V_{GS}=10$ V, $V_{DS}=400$ V, $R_G=2$ Ω, $I_D=16$ A
Rise time	t_r		71.1		ns	
Turn-off delay time	$t_{d(off)}$		103.9		ns	
Fall time	t_f		33.4		ns	



■ Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		37.1		nC	$I_D=16\text{ A}$, $V_{DS}=400\text{ V}$, $V_{GS}=10\text{ V}$
Gate-source charge	Q_{gs}		11.0		nC	
Gate-drain charge	Q_{gd}		13.8		nC	
Gate plateau voltage	$V_{plateau}$		6.7		V	

■ Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward current	I_S			30	A	$V_{GS} < V_{th}$
Pulsed source current	I_{SP}			90		
Diode forward voltage	V_{SD}			1.3	V	$I_S=30\text{ A}, V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		123.0		ns	$V_R=400\text{V}, I_S=16\text{ A},$ $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		0.73		μC	
Peak reverse recovery current	I_{rrm}		11.0		A	

■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^{\circ}\text{C}$.
- 5) $V_{DD}=100\text{ V}$, $R_G=50\text{ }\Omega$, $L=60\text{ mH}$, starting $T_j=25\text{ }^{\circ}\text{C}$.



■ Electrical Characteristics Diagrams

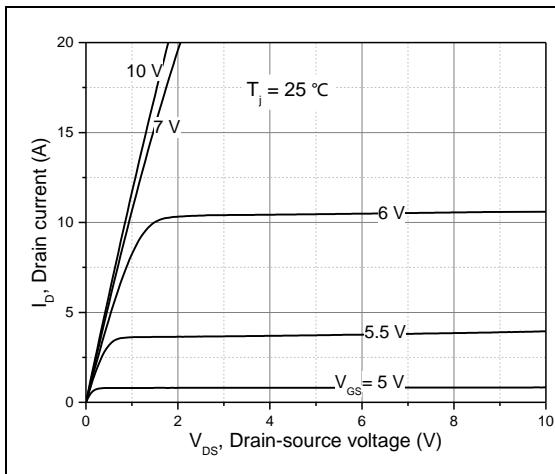


Figure 1, Typ. output characteristics

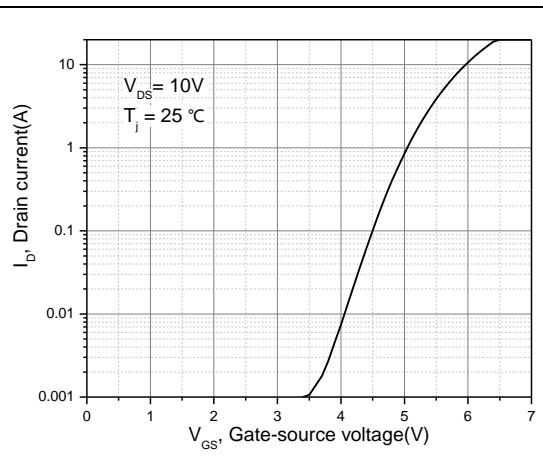


Figure 2, Typ. transfer characteristics

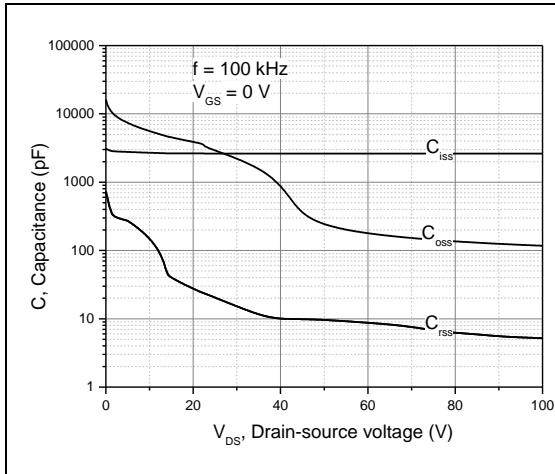


Figure 3, Typ. capacitances

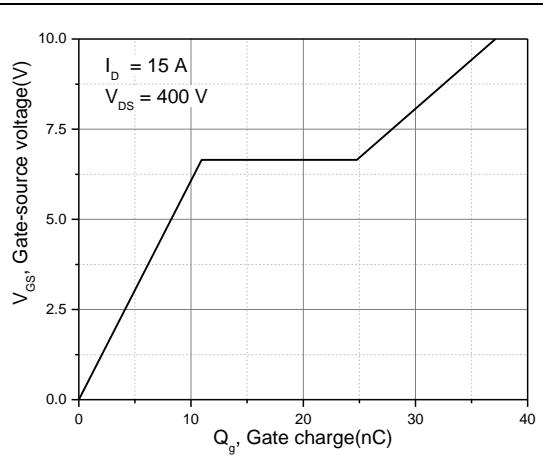


Figure 4, Typ. gate charge

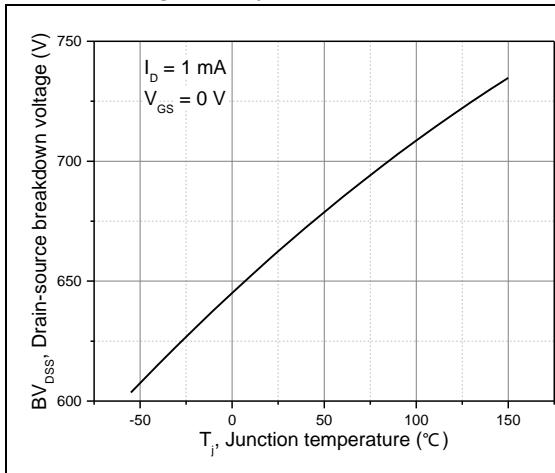


Figure 5, Drain-source breakdown voltage

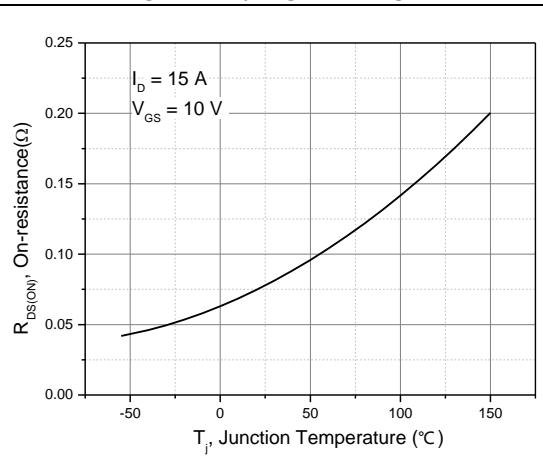


Figure 6, Drain-source on-state resistance

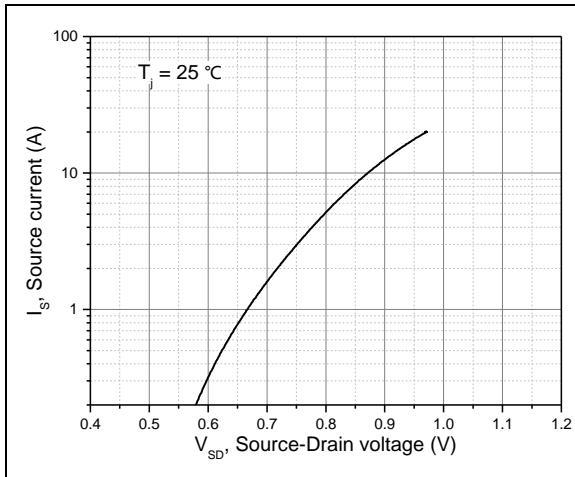


Figure 7, Forward characteristic of body diode

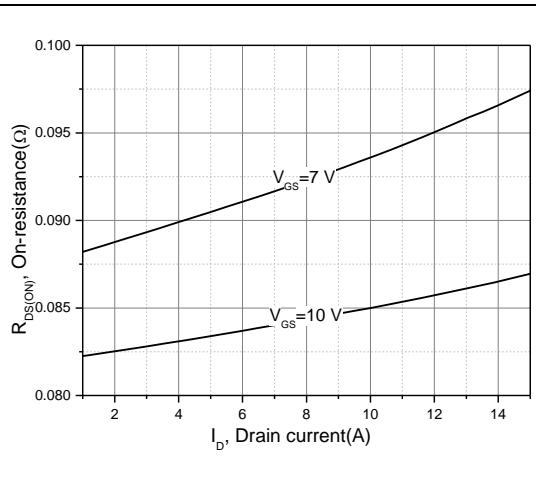


Figure 8, Drain-source on-state resistance

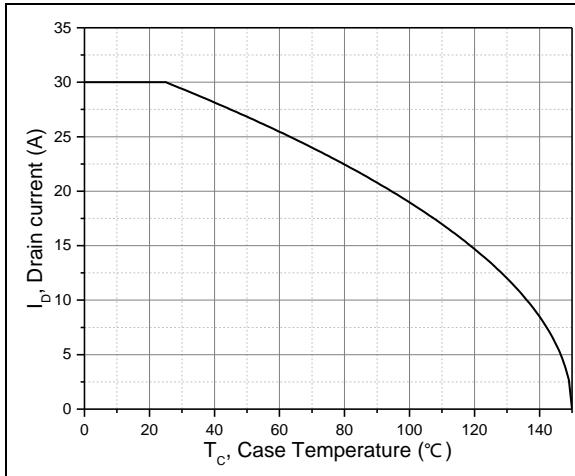


Figure 9, Drain current

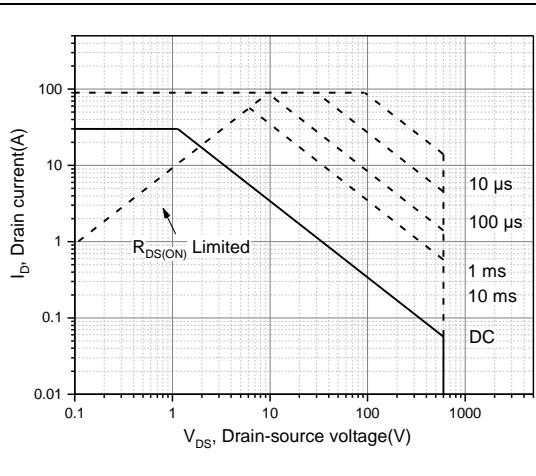
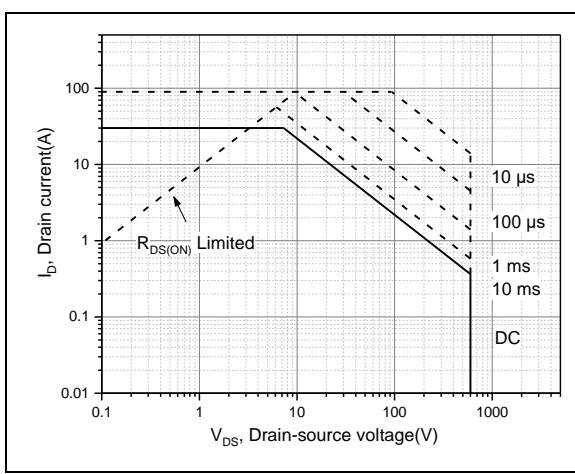
Figure 10, Safe operation area for TO263,
TO247, TO220 $T_c=25^\circ\text{C}$ 

Figure 11, Safe operation area for TO220F

 $T_c=25^\circ\text{C}$



■ Test circuits and waveforms

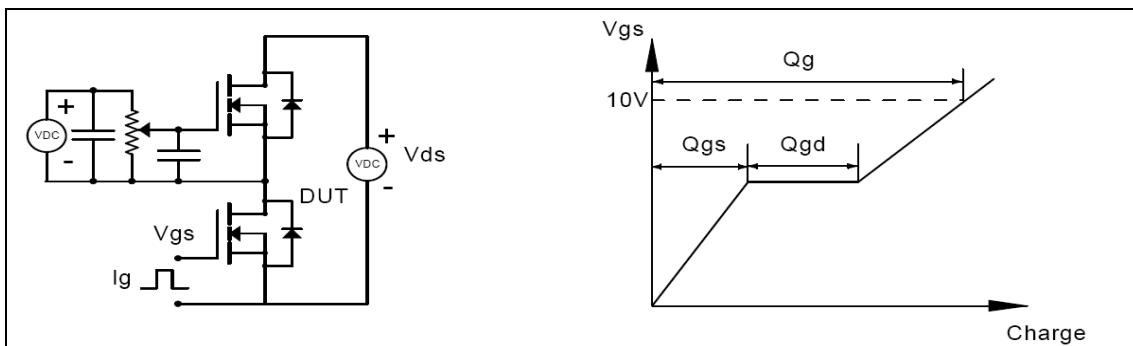


Figure 1, Gate charge test circuit & waveform

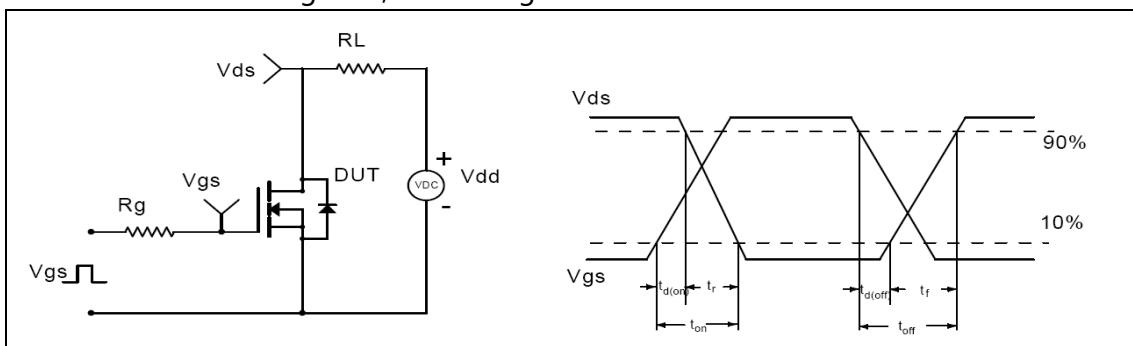


Figure 2, Switching time test circuit & waveforms

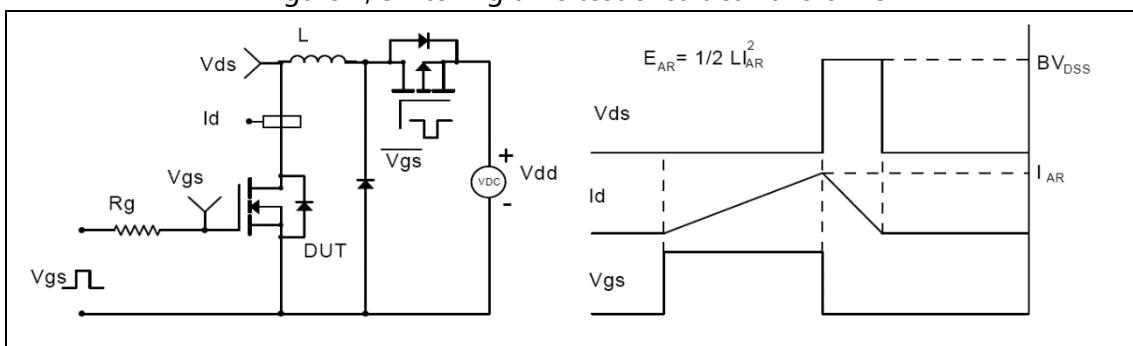


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

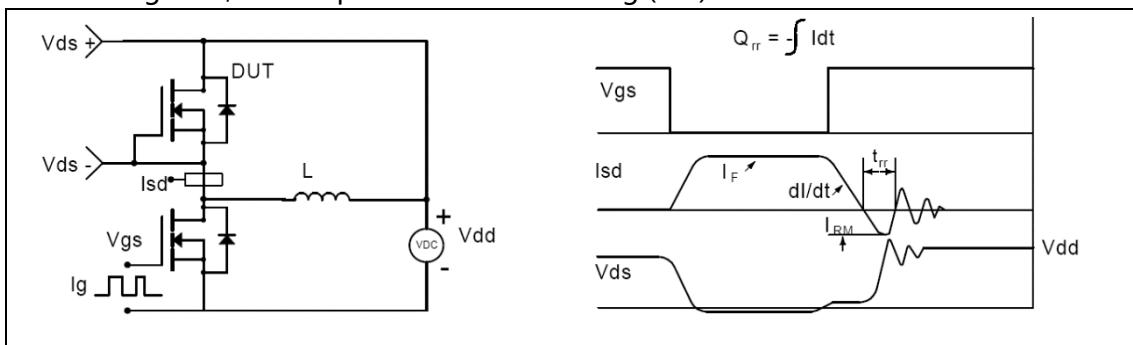
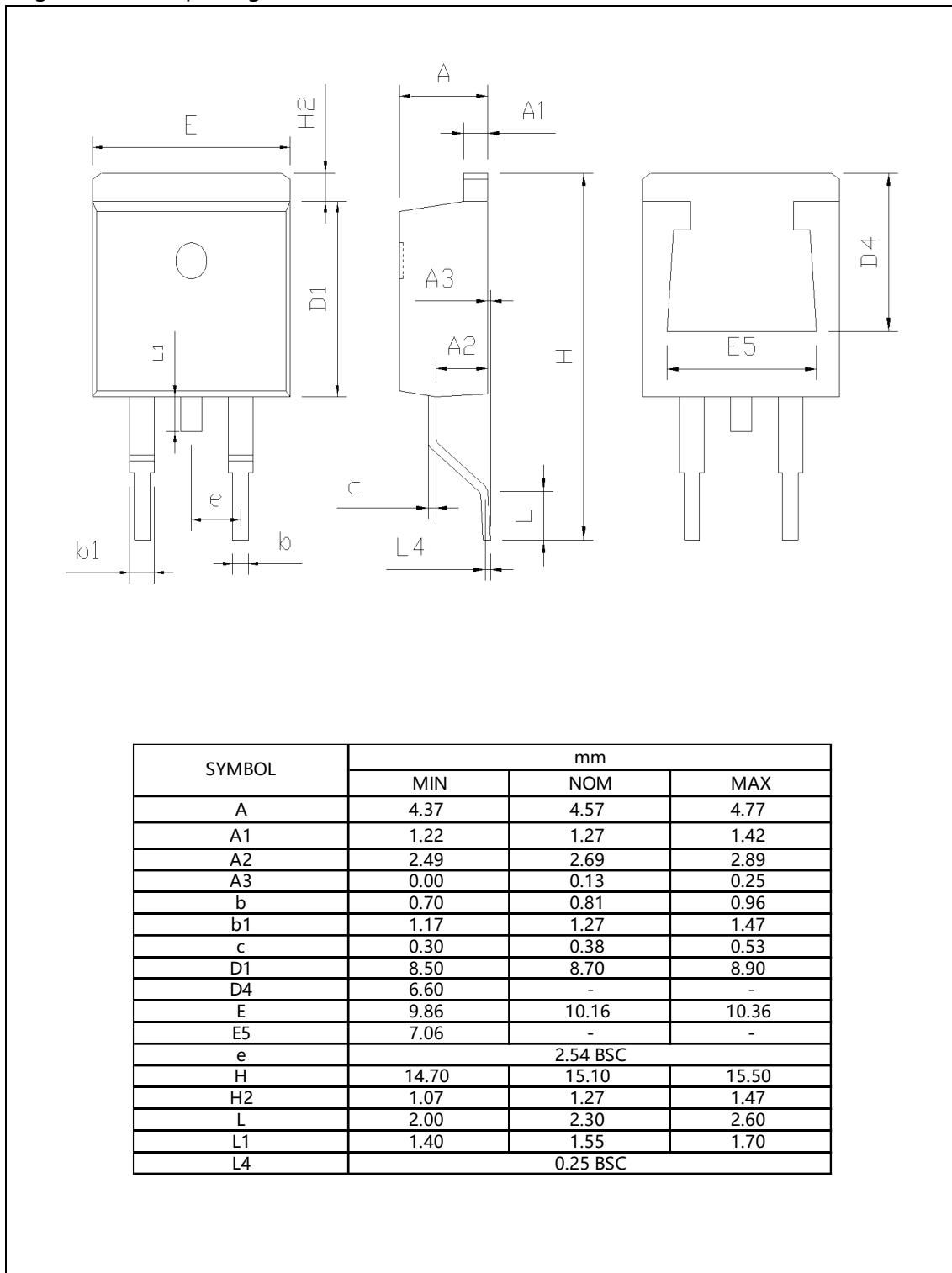


Figure 4, Diode reverse recovery test circuit & waveforms



■ Package Information

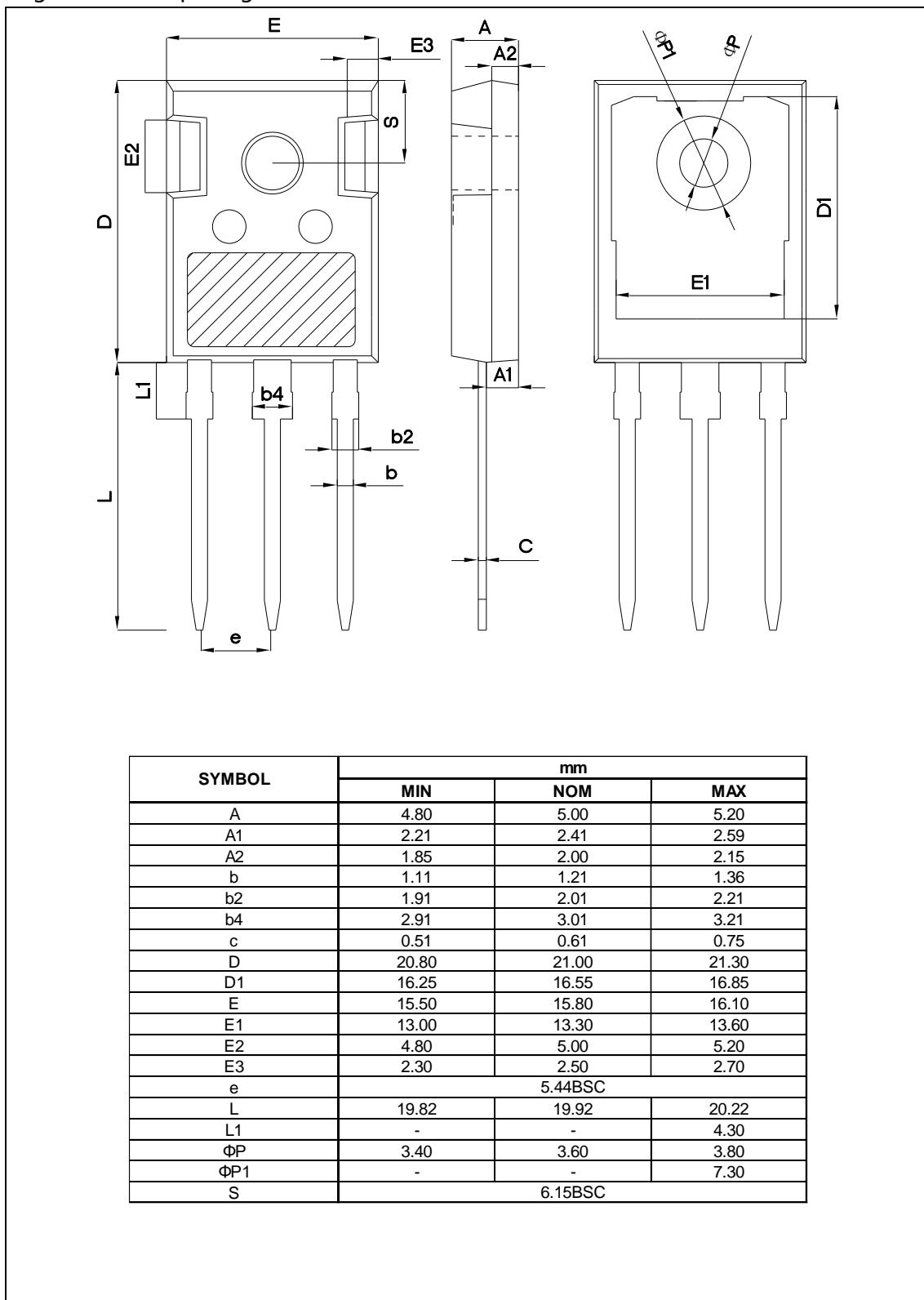
Figure1, TO263 package outline dimension





■ Package Information

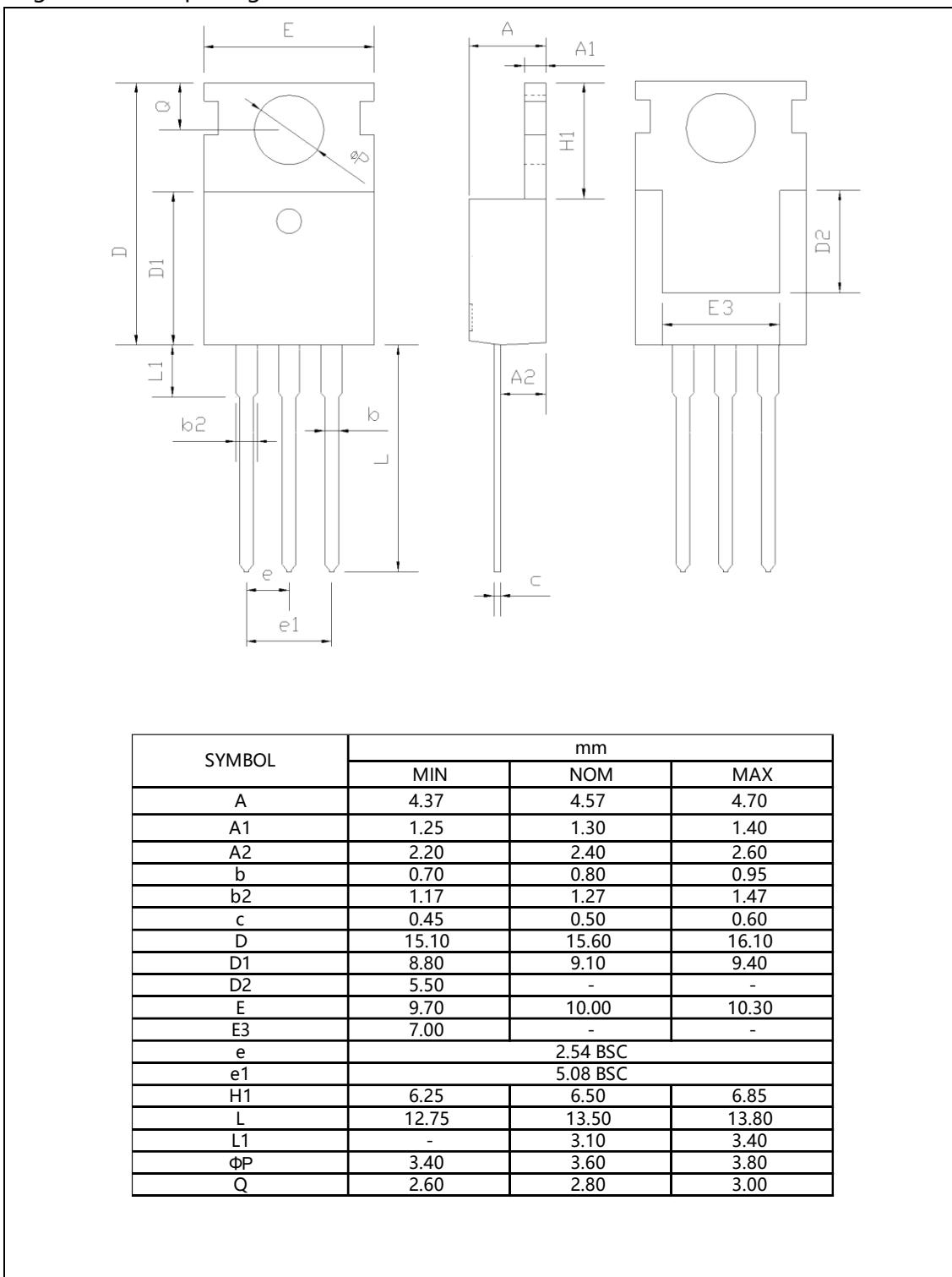
Figure2, TO247 package outline dimension





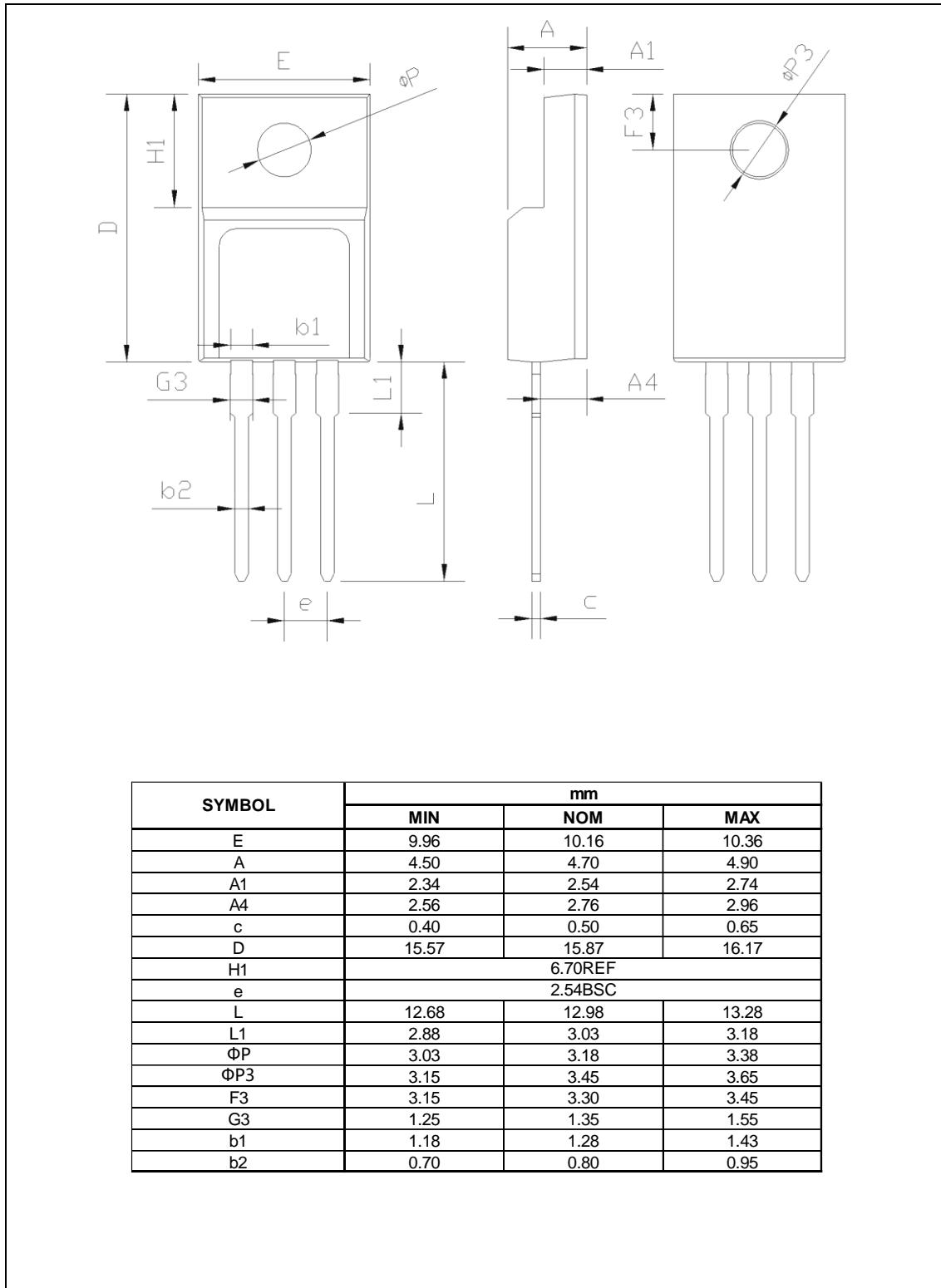
■ Package Information

Figure3, TO220 package outline dimension



■ Package Information

Figure4, TO220F package outline dimension





■ Ordering Information

Package	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO263	50	20	1000	6	6000
TO247	30	11	330	6	1980
TO220	50	20	1000	6	6000
TO220F	50	20	1000	6	6000

■ Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG60R108KZF	TO263	yes	yes	yes
OSG60R108HZF	TO247	yes	yes	yes
OSG60R108PZF	TO220	yes	yes	yes
OSG60R108FZF	TO220F	yes	yes	yes